



## Product Change Notification - LIAL-01MXFB070

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**Date:**

18 Jul 2018

**Product Category:**

8-bit PIC Microcontrollers; 16-Bit - Microcontrollers and Digital Signal Controllers; Interface-Controller Area Network (CAN)

**Affected CPNs:****Notification subject:**

CCB 3263, 3263.001-3263.002 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K and 160K wafer technologies available in 28L QFN-S (6x6mm), 28L QFN (6x6mm), 16L QFN (4x4mm) and 20L QFN (4x4mm) packages assembled at MTAI assembly site.

**Notification text:****PCN Status:**

Final notification.

**PCN Type:**

Manufacturing Change

**Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K and 160K wafer technologies available in 28L QFN-S (6x6mm), 28L QFN (6x6mm), 16L QFN (4x4mm) and 20L QFN (4x4mm) packages assembled at MTAI assembly site.

**Pre Change:**

Assembled at MTAI using gold (Au) bond wire, 3280 die attach, G700LTD molding compound and A194 lead frame material or assembled at NSEB using gold (Au) bond wire, 8200T die attach, G770HCD molding compound and C194 or EFTEC-64T lead frame material

**Post Change:**

Assembled at MTAI using palladium coated copper with gold flash (CuPdAu) bond wire, 3280 die attach, G700LTD molding compound and A194 lead frame material

**Pre and Post Change Summary:**

	Pre Change		Post Change
Assembly Site	Microchip Technology Thailand HQ (MTAI)	UTAC Thai Limited (UTL-1) LTD. (NSEB)	Microchip Technology Thailand HQ (MTAI)
Wire material	Au	Au	CuPdAu
Die attach material	3280	8200T	3280
Molding compound material	G700LTD	G770HCD	G700LTD
Lead frame material	A194	C194/ EFTEC-64T	A194

**Impacts to Data Sheet:**

None

**Change Impact:**



None

**Reason for Change:**

To improve on-time delivery performance by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at MTAI

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

July 11, 2018 (date code: 1828)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	March 2018				-->	June 2018					July 2018				
Workweek	08	09	10	11		22	23	24	25	26	27	28	29	30	31
Initial PCN Issue Date			X												
Qual Report Availability								X							
Final PCN Issue Date								X							
Estimated Implementation Date												X			

**Method to Identify Change:**

Traceability code

**Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

**Revision History:**

**March 07, 2018:** Issued initial notification.

**March 21, 2018:** Revised this initial notification to be issued to all affected customers.

**June 11, 2018:** Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on July 11, 2018

**July 18, 2018:** Re-issued final notification to include NSEB assembly site in the pre-change.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[PCN\\_LIAL-01MXFB070\\_Qual\\_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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To opt out of future offer or information emails (other than product change notification emails), click



here to go to [microchipDIRECT](#) and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

Affected Catalog Part Numbers (CPN)

DSPIC30F2010-20E/MMVAO  
DSPIC30F2010-20I/MMVAO  
DSPIC30F2010T-20E/MMVAO  
DSPIC30F2010T-20I/MMVAO  
MCP2515-E/MLVAO  
MCP2515T-E/MLVAO  
PIC16F616T-I/MLVAO  
PIC16F685T-E/MLVAO  
PIC16F688-I/MLVAO  
PIC16F688T-I/MLVAO  
PIC16F689T-I/MLVAO  
PIC16F883-E/MLVAO  
PIC16F883T-E/MLVAO  
PIC16F886-E/MLVAO  
PIC16F886T-E/MLVAO  
PIC16F886T-I/MLVAO  
PIC16HV616-I/MLVAO  
PIC16HV616T-I/MLVAO  
PIC16LF628A-I/MLVAO  
PIC16LF628AT-I/MLVAO  
PIC18F2480-E/MLVAO  
PIC18F2480T-E/MLVAO  
PIC18F2480T-I/MLVAO  
PIC18F2580T-I/MLVAO  
PIC18LF2520T-E/MLVAO